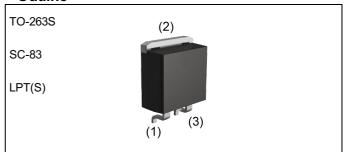
## Nch 800V 2A Power MOSFET

V <sub>DSS</sub>	800V
R <sub>DS(on)</sub> (Max.)	4.3Ω
I <sub>D</sub>	±2A
P <sub>D</sub>	62W

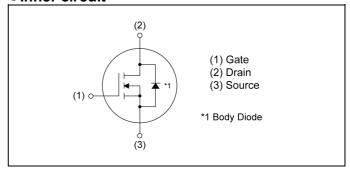
## Outline



## Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Parallel use is easy.
- 4) Pb-free plating; RoHS compliant

## •Inner circuit



Packaging specifications

· i donaç	Jing opcomoduomo	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	R8002ANJ

# Application

**Switching Power Supply** 

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	800	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±2	Α
Pulsed drain current	I <sub>DP</sub> *2	±8	Α
Gate - Source voltage	V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	I <sub>AS</sub> *3	1	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	0.265	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	62	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Downwortow	Cymah al	Values			l lesit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	2.01	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	800	-	-	V
		V <sub>DS</sub> = 800V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	-	100	μΑ
drain out on		T <sub>j</sub> = 125°C	-	-	-	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3.0	-	5.0	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.0A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	T <sub>j</sub> = 25°C	-	3.3	4.3	Ω
		T <sub>j</sub> = 125°C	-	7.2	-	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	6.6	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Cy reads ad	Conditions	Values			Unit
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Forward Transfer Admittance	$ Y_{fs} ^{*4}$ $V_{DS} = 10V, I_D = 1.0A$		0.5	-	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	250	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	130	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	15	-	
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 400V, V <sub>GS</sub> = 10V	-	20	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 1A	-	25	-	
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 402\Omega$	-	35	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	70	-	

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Downwater	Cymahal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg*4	V <sub>DD</sub> ≈ 400V	-	13	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 2A	-	3	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	7	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 400V, I <sub>D</sub> = 2A	-	7.0	-	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $^{\sim}$ 500 $\mu$ H, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , starting T<sub>j</sub>=25 $^{\circ}$ C

<sup>\*4</sup> Pulsed

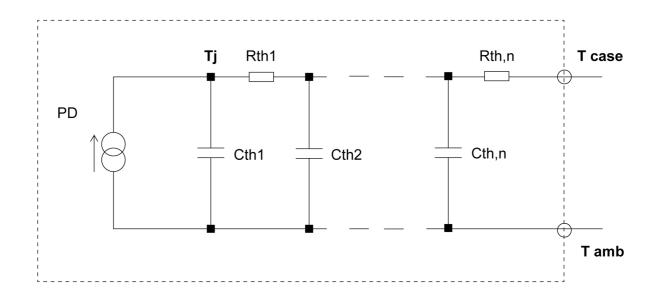
## ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Cumph of	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub> *1	T - 25°C	-	-	2	А
Pulse forward current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	8	А
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V$ , $I_S = 2A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *4		-	220	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	I <sub>S</sub> = 2A, V <sub>GS</sub> = 0V di/dt = 100A/μs	-	1.16	-	μC
Peak reverse recovery current	I <sub>rm</sub> *4	- α,, ατ 100/ γμο	-	10.5	-	Α

Typical transient thermal characteristics

Symbol	Value	Unit
R <sub>th1</sub>	0.8193	
R <sub>th2</sub>	h2 4.436	
R <sub>th3</sub>	65.84	

Symbol	Value	Unit
C <sub>th1</sub>	0.003182	
C <sub>th2</sub>	0.1798	Ws/K
C <sub>th3</sub>	0.9345	



### Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

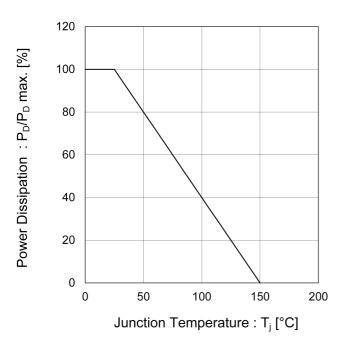


Fig.2 Maximum Safe Operating Area

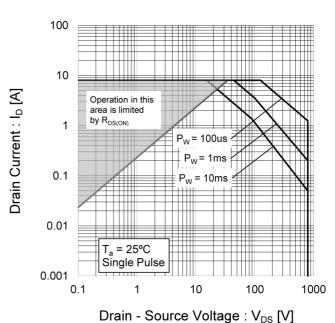


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

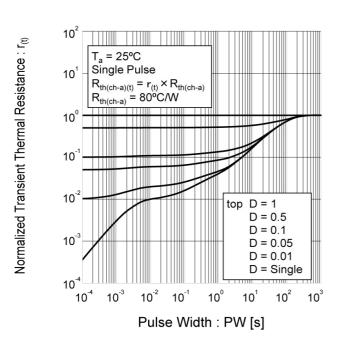
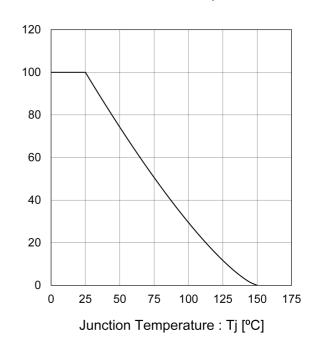


Fig.4 Avalanche Energy Derating Curve vs. Junction Temperature



Avalanche Energy : E $_{\mathsf{AS}}$  / E $_{\mathsf{AS}}$  max. [%]

## • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

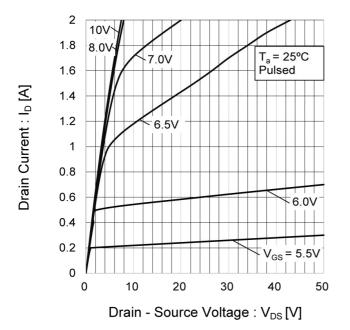
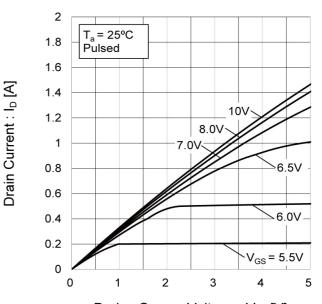


Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

## • Electrical characteristic curves

Fig.7 Normalized Breakdown Voltage vs.

Junction Temperature

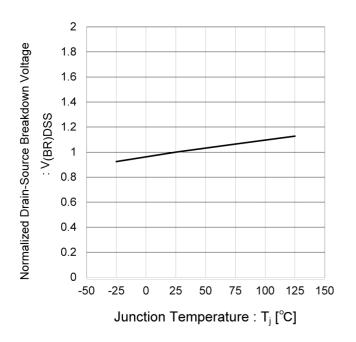


Fig.8 Typical Transfer Characteristics

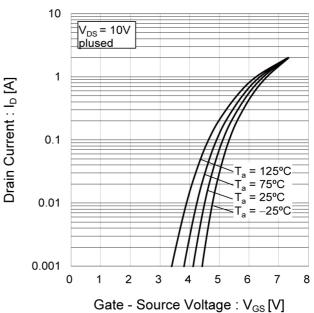


Fig.9 Normalized Gate Threshold Voltage vs. Junction Temperature

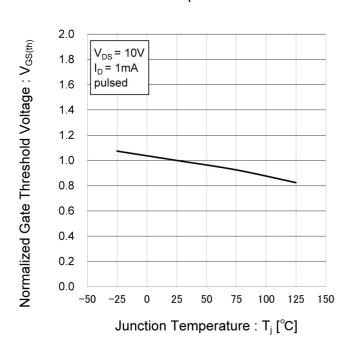
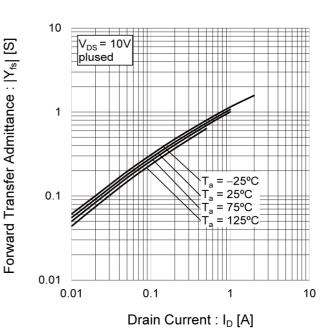


Fig.10 Forward Transfer Admittance vs. Drain Current



### Electrical characteristic curves

Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

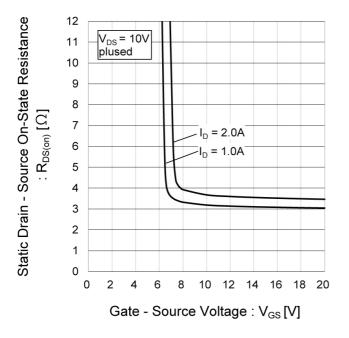


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

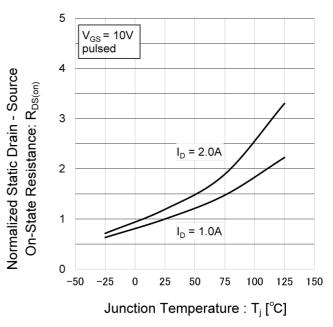


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

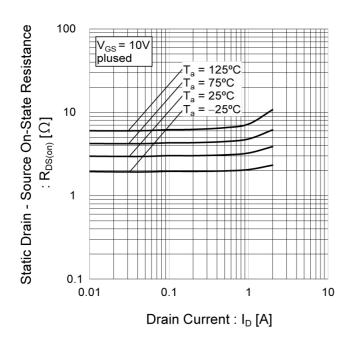
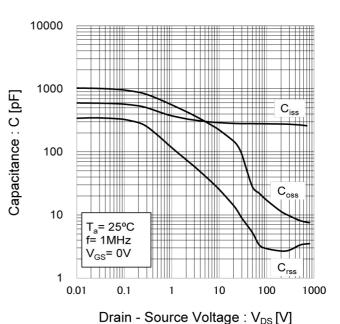


Fig.14 Typical Capacitance vs. Drain - Source Voltage



### Electrical characteristic curves

Fig.15 Switching Characteristics

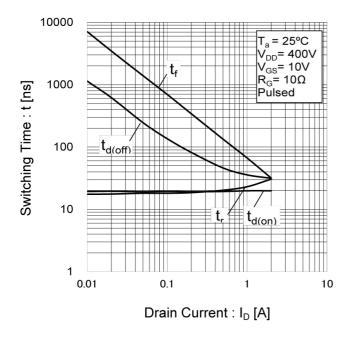
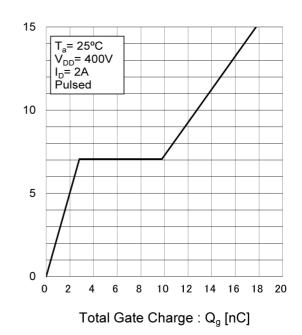


Fig.16 Dynamic Input Characteristics



Gate - Source Voltage :  $V_{GS}$  [V]

Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

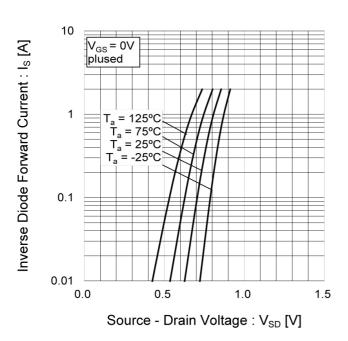
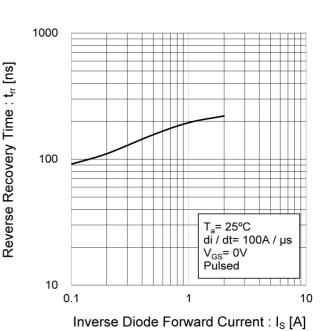


Fig.18 Reverse Recovery Time vs. Inverse Diode Forward Current



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

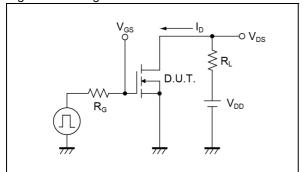


Fig.2-1 Gate Charge Measurement Circuit

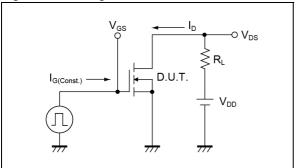


Fig.3-1 Avalanche Measurement Circuit

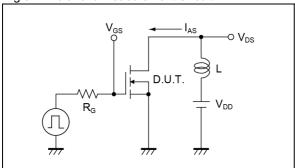


Fig.4-1 trr Measurement Circuit

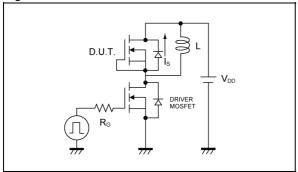




Fig.1-2 Switching Waveforms

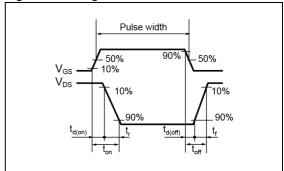


Fig.2-2 Gate Charge Waveform

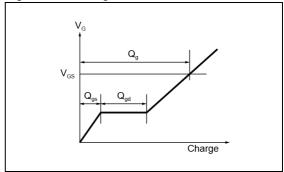


Fig.3-2 Avalanche Waveform

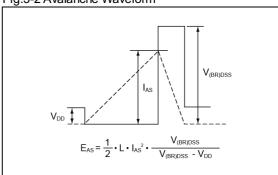
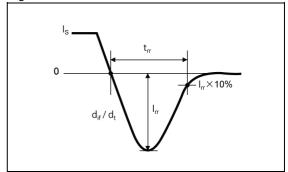
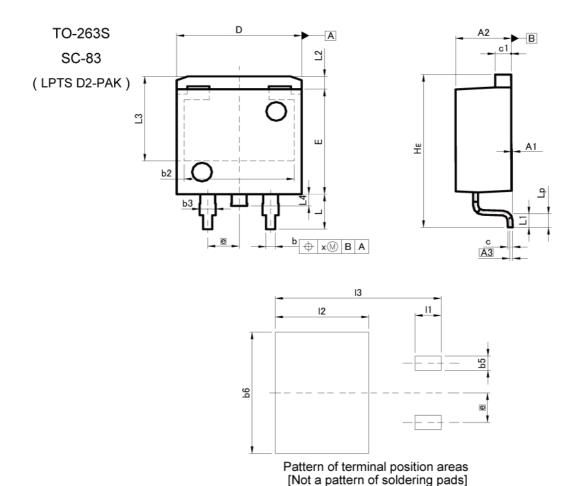


Fig.4-2 trr Waveform





## Dimensions



MILIMETERS MIN 0.00 4 20 INCHES DIM MIN 0.000 0.169 MAX 0.012 0.185 MAX 0.30 A1 4.70 4.30 **A**3 0.010 0.25 b 0.027 0.68 0.98 0.039 b2 0.350 8.90 b3 0.045 0.057 1.14 1.44 С 0.012 0.024 0.30 0.60 cī D 0.043 0.386 1.10 1.50 0.059 10.40 9.20 9.80 0.409 Έ 8.80 0.346 0.362 е 0.100 12.80 2.70 0.528 0.130 HE 13.40 0.504 3.30 0.106 LT 1.20 0.047

100						
DIM	DIM MILIME		INC	HES		
DIM	MIN	MAX	MIN	MAX		
b5	-	1.23	-	0.049		
b6	-	10.40	-	0.409		
. 11	_	2.10	-	0.083		
12	-	7.55	-	0.297		
13		13.40	_	0.528		

1.50 0.25

Dimension in mm/inches

0.90

1.10

7.25 1.00



0.043

0.285

0.035

0.059 0.010

L2

L3 L4

Lp

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CI ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.003

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Notice – WE Rev.001



## R8002ANJ - Web Page

Part Number	R8002ANJ
Package	LPTS(D2PAK)
Unit Quantity	1000
Minimum Package Quantity	1000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes